

HIGH TEMP FAN HEAT SINK

FEATURES

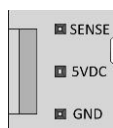
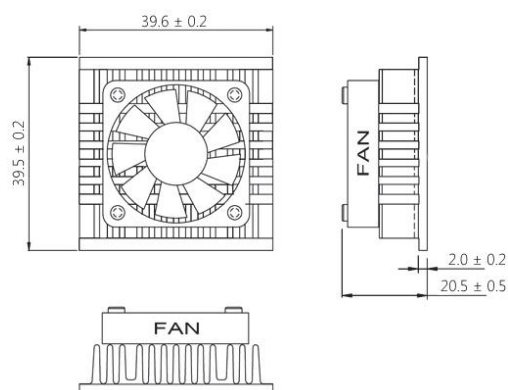
- Moderate surface area of 40 x 40 x 21 (mm)
- Extruded Plate Fins offer a Thermal Resistance(R_{TH}) of 1.79
- Maximum Operating Temperature of 90°C
- Common 5VDC @ 0.5A(max), USB 2.0 Fan Electrical Specifications
- Operating Temperature Range of -10°C to 90°C
- 0.2mm thick Thermally Conductive, Fiberglass Mesh, adhesive mounting tape
- Mates with Molex 22-11-2032 or equivalent

APPLICATIONS

- Designed for use with the BytePipe_x9002 SOM with HDK (or custom designs)

GENERAL DESCRIPTION

The FAN-1005 is designed to absorb and disperse heat away from the RF SOM during operation. It features thermally conductive adhesive allowing it to be permanently installed on a SOM, and a keyed 3-pin connector that mates to the power connection on the HDK.



Pinout of mating connector (top view)



Shown as installed on a SOM and HDK (not included)